



Features:

- Isolated mounting base 3000V~
 - Pressure contact technology with Increased power cycling capability
 - Space and weight saving
- Typical Applications**
- AC/DC Motor drives
 - Various rectifiers
 - DC supply for PWM inverter

V_{RSM}	V_{RRM}	Type & Outline
900V	800V	MDx90-08-223F3
1100V	1000V	MDx90-10-223F3
1300V	1200V	MDx90-12-223F3
1500V	1400V	MDx90-14-223F3
1700V	1600V	MDx90-16-223F3
1900V	1800V	MDx90-18-223F3

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T_j (°C)	VALUE			UNIT
				Min	Type	Max	
$I_{F(AV)}$	Mean forward current	180° half sine wave 50Hz Single side cooled, $T_c=100^\circ C$	150			90	A
$I_{F(RMS)}$	RMS forward current		150			141	A
I_{RRM}	Repetitive peak current	at V_{RRM}	150			8	mA
I_{FSM}	Surge forward current	10ms half sine wave	150			2.30	KA
I^2t	I^2T for fusing coordination	$V_R=0.6V_{RRM}$				26	$A^2s \cdot 10^3$
V_{FO}	Threshold voltage		150			0.80	V
r_F	Forward slop resistance					1.70	$m\Omega$
V_{FM}	Peak forward voltage	$I_{FM}=270A$	25			1.33	V
$R_{th(j-c)}$	Thermal resistance Junction to case	At 180° sine Single side cooled per chip				0.470	°C /W
$R_{th(c-h)}$	Thermal resistance case to heatsink	At 180° sine Single side cooled per chip				0.2	°C /W
V_{iso}	Isolation voltage	50Hz, R.M.S, t=1min, $I_{iso}:1mA$ (max)		3000			V
F_m	Terminal connection torque(M5)				4		$N \cdot m$
	Mounting torque(M6)				6		$N \cdot m$
T_{stg}	Stored temperature		-40			125	°C
W_t	Weight				160		g
Outline		223F3					

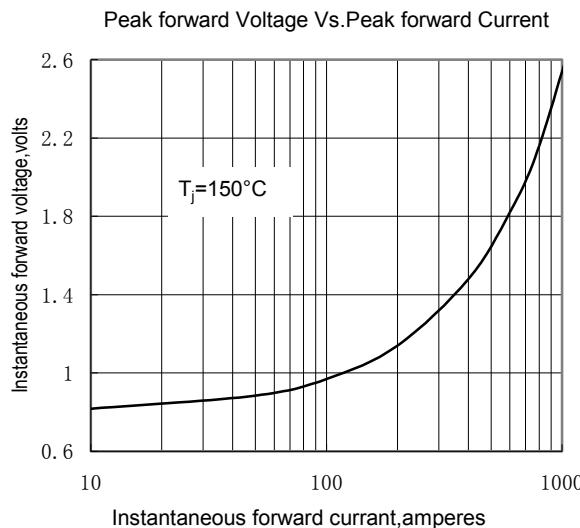


Fig.1

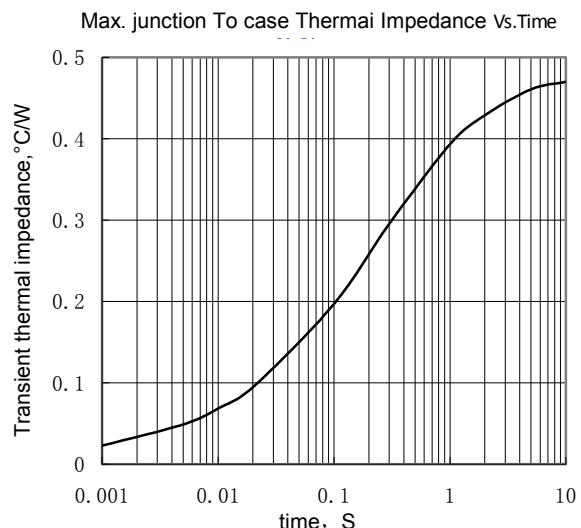


Fig.2

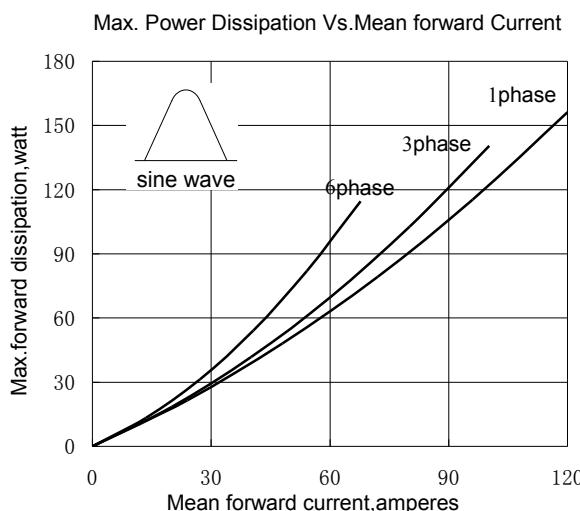


Fig.3

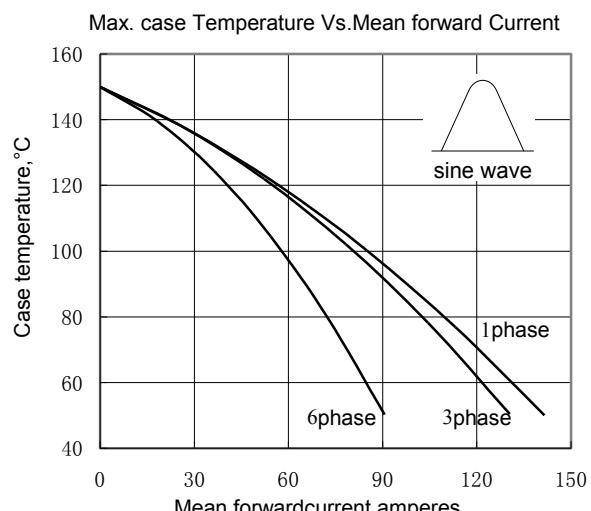


Fig.4

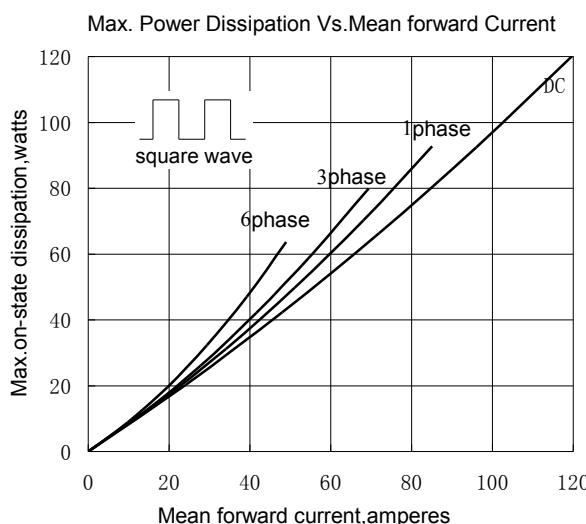


Fig.5

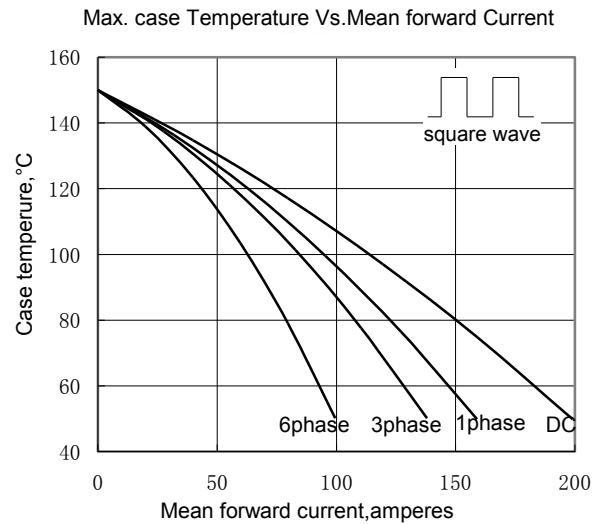


Fig.6

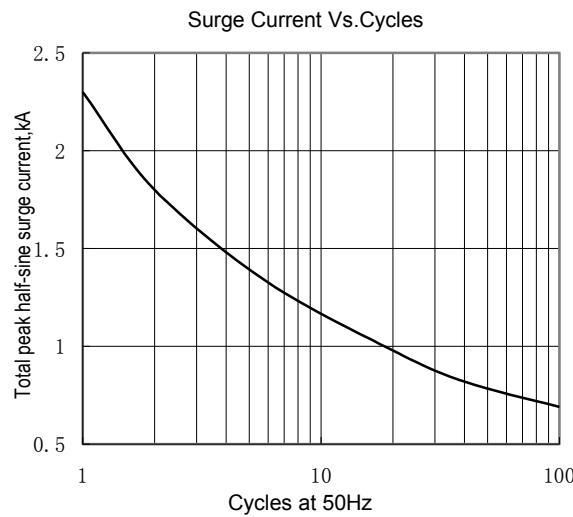


Fig.7

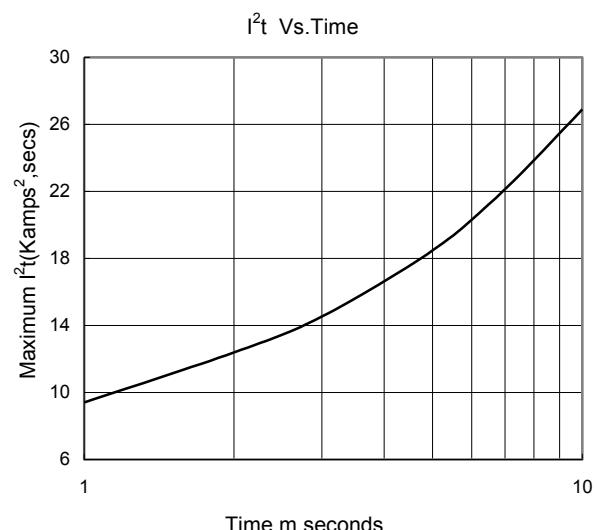


Fig.8

Outline:

